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### **RX240128A-FHW**

### **SPECIFICATION**

### **CUSTOMER:**

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

Release DATE:



# **Revision History**

VERSION	DATE	REVISED PAGE NO.	Note
0	2011/06/13		First issue
Α	2012/11/20		Modify Backlight
			Information
В	2013/02/07		Modify Display
			Command
			Correct VLCD
			Correct pin
			Description.
С	2014/09/03		Remove IC
			information
D	2016/01/15		Add Pull Tape
E	2016/02/25		Modify Precautions in
			use of LCD Modules
			& Static electricity
			test



## **Contents**

- 1. General Specification
- 2. Module Classification Information
- 3.Interface Pin Function
- 4. Contour Drawing
- 5. Optical Characteristics
- 6. Absolute Maximum Ratings
- 7. Electrical Characteristics
- 8.Backlight Information
- 9.Reliability
- 10.Inspection specification
- 11.Precautions in use of LCD Modules
- 12. Material List of Components for RoHs
- 13. Recommendable Storage



## 1.General Specification

The Features is described as follow:

■ Module dimension: 98.7 x 67.7 x 9.5 mm

■ View area: 92.0 x 53.0 mm

Active area: 83.975 x 44.775 mm

■ Number of dots: 240 x 128

■ Dot size: 0.325 x0.325 mm

■ Dot pitch: 0.35 x 0.35 mm

■ LCD type: FSTN Positive, Transflective

■ Duty: 1/128

■ View direction: 6 o'clock

■ Backlight Type: LED White

■ IC: UC1608



### 2. Module Classification Information

<u>R</u>	<u>X</u>	240128	<u>A</u>	_	<u>F</u>	<u>H</u>	W
①	2	3	4	_	(5)	6	7

Item	Description						
1	R : Raystar Optronics Inc.						
2	Dioploy	C: Character Type,		T:TAB Type			
	G: Graphic Type			X:COG Type			
3	Display Font :						
4	Serials code :						
		P→TN Positive, Gray		V→FSTN Ne	egative, Blue		
		N→TN Negative,		T→FSTN Ne	egative, Black		
		L→VA Negative		D→FSTN N	egative (Double film)		
		H→ HTN Positive, Gray		F→FSTN Po	ositive		
5	LCD	I→HTN Negative, Black		K→FSC Neg			
		U→HTN Negative, Blue		S→FSC Pos			
		B→STN Negative, Blue			gative, Black		
		G→STN Positive, Gray		C→CSTN Negative, Black			
		Y→STN Positive, Yellow	Green	A→ASTN Negative, Black			
		A: Reflective, N.T, 6:00		K: Transflective, W.T,12:00			
	Polarizer	D: Reflective, N.T, 12:0		1: Transflective, U.T,6:00			
	Type,	G: Reflective, W. T, 6:00			ctive, U.T.12:00		
	Temperature	J: Reflective, W. T, 12:0			ssive, N.T,6:00		
6	range,	0: Reflective, U. T, 6:00		F: Transmissive, N.T,12:00			
	3-7	3: Reflective, U. T, 12:0			sive, W. T, 6:00		
	View	B: Transflective, N.T,6:0			ssive, W.T,12:00		
	direction	E: Transflective, N.T.12			ssive, U. T, 6:00		
		H: Transflective, W.T,6:			ssive, U.T,12:00		
	1	N→ Without backlight		D, White	H→LED, High light White		
		P→EL, Blue		), Amber	S→LED, Full color		
		T→EL, Green	R→LED		J→DIP LED, Blue		
7	Backlight	D→EL, White		), Orange	K→DIP LED, White		
	Daroning	M→EL, Yellow Green	B→LED		E→DIP LED, Yellow		
		F→CCFL, White		, Dual color	L→DIP LED, Amber		
		Y→LED, Yellow Green	C→LED	), Full color	I→DIP LED, Red		
		G→LED, Green					



## **3.Interface Pin Function**

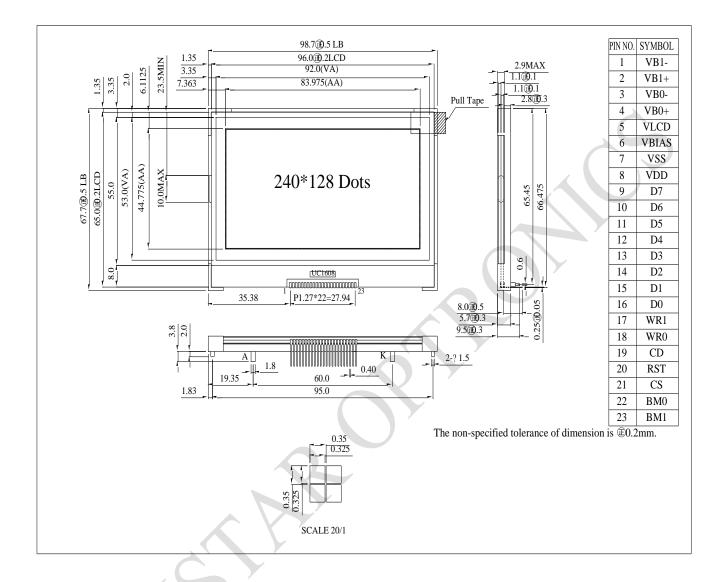
Pin No.	Symbol	Туре		Description					
1	VB1-		LCD Bia	as Voltages.	These are th	ne voltage s	ource to		
	\/D4 ·		provide	SEG driving	currents. Th	nese voltage	s are		
2	VB1+		_	generated internally. Connect capacitors of CBX between					
3	VB0-	PWR		nd VBX–.	_				
				istance of the		•			
4	VB0+			ving strength					
			quality i	e the trace re mage.	2515tallCe 15	CHIICAI III AC	nieving nign		
5	VLCD	PWR	1	D Power Su	ıpply. Conne	ct these pin	s together.		
			This is t	he reference	voltage to	generate the	actual SEG		
			driving v	oltage. VBI	AS can be us	sed to fine to	ine VLCD by		
6	VBIAS	ı	external	variable res	istors. Intern	hal resistor n	etwork has		
	VDIAG	'	been pr	ovided to sin	nplify externa	al trimming o	circuit.		
				application,			capacitor		
			betweer	NBIAS and	VSS to redu	uce noise.			
7	VSS	PWR	Ground						
8	VDD	PWR	Supply '	Voltage for lo	ogic				
9	D7	1		tional bus fo	r both serial	and parallel	host		
10	D6		interface		noot DIOI to	CCK Dial #	- CD4		
11	D5		ın senai	modes, con		SCK, D[3] (	5 SDA,		
		7		BM=1x (Parallel)	BM=0x (Parallel)	BM=01 (S9)	BM=00 (S8/S8uc)		
12	D4		D0	D0	D0/D4	SCK	SCK		
13	D3	I/O	D1 D2	D1 D2	D1/D5 D2/D6	_ _	_		
14	D2		D3	D3	D3/D7	SDA	SDA		
15	D1		D4 D5	D4 D5	-	_ _	_		
13	וט		D6	D6	-	S9	S8/S8uc		
16	D0		D7	D7	0	1	1 1		
			Connect unused pins to VDD or VSS.						
17	\\/D4	ı	WR[1:0] controls the read/write operation of the host						
17	WR1	I	interface	e. See Host	Interface sed	ction for mor	e detail.		



18	WR0		In parallel mode, WR[1:0] meaning depends on whether the interface is in the 6800 mode or the 8080 mode. In serial interface modes, these two pins are not used, connect them to VSS.				
					a or Display data for read/write		
19	CD	I	operation	. In S9 m	ode, CD pin is not used. Connect CD to		
			VSS whe	n not use	d. "L": Control data "H": Display data		
			When RS	T="L", all	control registers are re-initialized by		
			their defa	ult states			
	DOT		Since UC	1608x ha	s built-in Power-ON-Reset and		
20	RST	I	Software	Reset co	mmand, RST pin is not required for		
					ion. When RST is not used, connect the		
			pin to VD	•			
			<u>'</u>		hip is selected when CS="H". When the		
21	CS	I	-				
					d, D[7:0] will be high impedance.		
					erface bus mode is determined by		
			BM[1:0] a	nd D[7:6]	by the following relationship:		
22	BM0		BM[1:0]	D[7:6]	Mode		
			11	Data	6800/8-bit		
			10	Data	8080/8-bit		
		ı	01	0X	6800/4-bit		
		•	00	0X	8080/4-bit		
			01 10 3-wire SPI w/ 9-bit token (S9: conventional)				
23	BM1		00	10	4-wire SPI w/ 8-bit token (S8: conventional)		
			00	11	3- or 4-wire SPI w/ 8-bit token (S8uc: Ultra-Compact)		



## 4.Contour Drawing



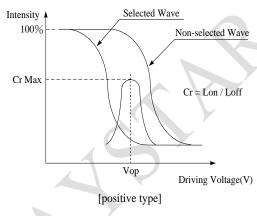


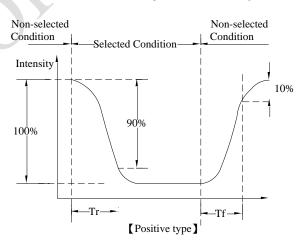
## **5.Optical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	θ	CR <u>≥</u> 2	0	_	30	ψ= 180°
	θ	CR <u>≥</u> 2	0	_	60	ψ= 0°
	θ	CR <u>≥</u> 2	0	_	45	ψ= 90°
	θ	CR <u>≥</u> 2	0	1	45	ψ= 270°
Contrast Ratio	CR	_		5	_	_
Poononce Time	T rise	- /	1	200	300	ms
Response Time	T fall		7	250	350	ms

#### **Definition of Operation Voltage (Vop)**

#### **Definition of Response Time (Tr, Tf)**





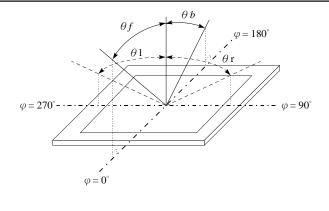
#### **Conditions:**

Operating Voltage : Vop Viewing Angle( $\theta$ ,  $\phi$ ) :  $0^{\circ}$ ,  $0^{\circ}$ 

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

### Definition of viewing angle(CR≥2)







# **6.Absolute Maximum Ratings**

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	$^{\circ}$
Storage Temperature	T <sub>ST</sub>	-30	_	+80	Ŝ
Logic supply voltage	V <sub>DD</sub>	-0.3	_	+4.0	<b>&gt;</b>
LCD Generator supply voltage	V <sub>DD</sub> 2	-0.3	-	+4.0	<b>V</b>
LCD Generated voltage	VLCD	-0.3		+17.0	V



### 7. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For	V V		2.7	2.8~3.3	3.6	V
Logic	V <sub>DD</sub> -V <sub>SS</sub>		2.1	2.0~3.3	3.0	V
		Ta=-20°C	_	_		<
Supply Voltage For LCM	$V_{LCD}$	Ta=25°C	15.2	15.5	15.8	V
		Ta=70°C	_		>-	V
Input High Volt.	Vıн	_	0.8 V <sub>DD</sub>		_	V
Input Low Volt.	VIL	- (	->	_	0.2 V <sub>DD</sub>	V
Output High Volt.	Vон		0.8 V <sub>DD</sub>	_	_	V
Output Low Volt.	Vol	( ) >	_	_	0.2 V <sub>DD</sub>	V
Supply Current(No						
include	I <sub>DD</sub>	V <sub>DD</sub> =3.0V	_	1.1	_	mA
LED Backlight)						

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.



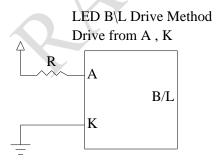
## 8.Backlight Information

#### **Specification**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	86.4	96	120	mA	V=3.5V
Supply Voltage	V	3.3	3.5	3.7	V	4 ( ) ~
Reverse Voltage	VR	_	_	5	V	-
Luminance (Without LCD)	IV	400	500	_	CD/M2	ILED=96mA
Waya Langth	X	0.28	0.3	0.32	1	ILED=96mA
Wave Length	Y	0.28	0.3	0.32		ILED-96IIIA
LED Life Time				<b>\</b>		ILED≦96mA
(For Reference	_	_	50K	<b>)</b> –	Hr.	25°C,50-60%RH,
only)						(Note 1)
Color	White		<b>7</b>			

Note: The LED of B/L is drive by current only; driving voltage is only for reference To make driving current in safety area (waste current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.





## 9. Reliability

	Environmental Test		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times	

Content of Reliability Test (Wide temperature, -20°C~70°C)

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



# 10.Inspection specification

NO	Item	Criterion			AQL	
	1.1 Missing vertical, horizontal segment, segment contrast					
		defect.				
		1.2 Missing character, dot or icon.				
		1.3 Display malfunction.				
01	Electrical Testing	1.4 No function or no display.				
	resung	1.5 Current cons	sumption e	exceeds product sp	pecifications.	
		1.6 LCD viewing	angle def	fect.		
		1.7 Mixed produ	ct types.			
		1.8 Contrast def	ect.			
	Black or white	2.1 White and b	lack spots	on display $\leq$ 0.25	mm, no more than	
02	spots on LCD	three white c	r black sp	ots present.	Y	2.5
02	(display only)	2.2 Densely spa	ced: No m	ore than two spots	s or lines within	2.5
	(areplay erriy)	3mm			1	
		3.1 Round type : As following drawing				
		Ф=( x + y ) /	2	SIZE	Acceptable Q TY	
				Ф≦0.10	Accept no dense	
				0.10<Φ≦0.20	2	
				0.20<Φ≦0.25	1	2.5
		1		0.25<Ф	0	2.0
	LCD black	X	1			
	spots, white	<b>→</b>	<u>¥</u> .			
03	spots,	• •	<b>x</b> Y			
	contamination		Te e			
	(non-display)	3.2 Line type : (/	As followin	g drawing)		
		0.00	Length	Width	Acceptable Q TY	
1		→ <u>* w</u>		W≦0.02	Accept no dense	
			L≦3.0	0.02 <w≦0.03< td=""><td>2</td><td>2.5</td></w≦0.03<>	2	2.5
		87E.0	L≦2.5	0.03 <w≦0.05< td=""><td>2</td><td></td></w≦0.05<>	2	
	-			0.05 < W	As round type	





04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size $\Phi$ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$	Acceptable Q TY Accept no dense 3 2 0	2.5
			Total Q TY	3	





NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
		Symbols Define: x: Chip length y:	Chip width z: Chip t	hickness	
			Glass thickness a: LCD		
		L: Electrode pad length		oldo lolligui	
		6.1 General glass chip	:		
		6.1.1 Chip on panel sur	face and crack between	panels:	
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing	x≦1/8a	
06	Chipped		area		2.5
	glass	1/2t < z≦2t	Not exceed 1/3k	x≦1/8a	
		6.1.2 Corner crack:	chips, x is total length of	y	
		z: Chip thickness	y: Chip width	x: Chip length	
Q		Z≦1/2t	Not over viewing area	x≦1/8a	
	,	1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or more	e chips, x is the total leng	yth of each chip.	



NO	Item	Criterion	AQL
		Symbols:  x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:	
		Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z	
		y: Chip width x: Chip length z: Chip thickness	
		$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a} \qquad 0 < z \le t$	
06	Glass crack	6.2.2 Non-conductive portion:	2.5
		y: Chip width x: Chip length z: Chip thickness	
		$y \le L$ $x \le 1/8a$ $0 < z \le t$	
0		<ul> <li>If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</li> <li>If the product will be heat sealed by the customer, the alignment mark not be damaged.</li> <li>6.2.3 Substrate protuberance and internal crack.</li> </ul>	
		y: width x: length	
		y. width $x$ . length $y \le 1/3L$ $x \le a$	
		y	



NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
		8.1 Illumination source flickers when lit.	0.65
08	Backlight elements	8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.	2.5
		8.3 Backlight doesn't light or color wrong.	0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.	2.5 0.65
		9.2 Bezel must comply with job specifications.	0.03
		<ul><li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li><li>10.2 COB seal surface may not have pinholes through to the</li></ul>	2.5
		IC.	2.5
		10.3 The height of the COB should not exceed the height indicated in the assembly diagram.	0.65
		10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.	
		10.5 No oxidation or contamination PCB terminals.	2.5
10	PCB · COB	10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	
		10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
	4	10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.	2.5
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5
Y		X * Y<=2mm2	
7		11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections,	2.5
11	Soldering	oxidation or icicle.	
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65





NO	Item	Criterion	AQL
NO 12	General appearance	<ul> <li>12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.</li> <li>12.2 No cracks on interface pin (OLB) of TCP.</li> <li>12.3 No contamination, solder residue or solder balls on product.</li> <li>12.4 The IC on the TCP may not be damaged, circuits.</li> <li>12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.</li> <li>12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.</li> <li>12.7 Sealant on top of the ITO circuit has not hardened.</li> <li>12.8 Pin type must match type in specification sheet.</li> <li>12.9 LCD pin loose or missing pins.</li> <li>12.10 Product packaging must the same as specified on packaging specification sheet.</li> </ul>	AQL  2.5  0.65  2.5  2.5  2.5  0.65  0.65  0.65  0.65
		<ul><li>12.11 Product dimension and structure must conform to product specification sheet.</li><li>12.12 Visual defect outside of VA is not considered to be rejection.</li></ul>	0.65



#### 11.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Raystar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.



### 12. Material List of Components for RoHs

1. RAYSTAR Optronics. Inc. hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

- 2.Process for RoHS requirement: (only for RoHS inspection)
  - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
  - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.



## 13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



Page: 1

		raye. i				
	LCM Sample	Estimate Feedback Sheet				
Module Number :						
1 · Panel Specification :						
1. Panel Type:	□ Pass	□ NG ,				
2. View Direction:	□ Pass	□ NG ,				
3. Numbers of Dots:	□ Pass	□ NG ,				
4. View Area:	□ Pass	□ NG ,				
5. Active Area:	□ Pass	□ NG ,				
6.Operating Temperature:	□ Pass	□ NG ,				
7.Storage Temperature:	□ Pass	□ NG ,				
8.Others:	•					
2 · Mechanical Specification :						
1. PCB Size:	□ Pass	□ NG ,				
2.Frame Size :	□ Pass	□ NG ,				
3.Materal of Frame:	□ Pass	□ NG ,				
4.Connector Position:	□ Pass	□ NG ,				
5.Fix Hole Position:	□ Pass	□ NG ,				
6.Backlight Position:	□ Pass	□ NG ,				
7. Thickness of PCB:	□ Pass	□ NG ,				
8. Height of Frame to PCB:	□ Pass	□ NG ,				
9.Height of Module:	□ Pass	□ NG ,				
10.Others:	□ Pass	□ NG ,				
3 · Relative Hole Size :						
1.Pitch of Connector:	□ Pass	□ NG ,				
2.Hole size of Connector:	□ Pass	□ NG ,				
3.Mounting Hole size:	□ Pass	□ NG ,				
4.Mounting Hole Type:	□ Pass	□ NG ,				
5.Others:	□ Pass	□ NG ,				
4 · Backlight Specification :						
1.B/L Type:	□ Pass	□ NG ,				
2.B/L Color:	□ Pass	□ NG ,				
3.B/L Driving Voltage (Reference for LED Type) : □ Pass □ NG ,						
4.B/L Driving Current:	□ Pass	□ NG ,				
5.Brightness of B/L:	□ Pass	□ NG ,				
6.B/L Solder Method:	□ Pass	□ NG ,				
7.Others:	□ Pass	□ NG ,				

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Module Number :				
5 · Electronic Characteristics of Module :				
1.Input Voltage:	□ Pass	□ NG ,		
2.Supply Current:	□ Pass	□ NG ,		
3.Driving Voltage for LCD:	□ Pass	□ NG ,		
4.Contrast for LCD:	□ Pass	□ NG ,		
5.B/L Driving Method:	□ Pass	□ NG ,		
6.Negative Voltage Output:	□ Pass	□ NG ,		
7.Interface Function:	□ Pass	□ NG ,		
8.LCD Uniformity:	□ Pass	□ NG ,		
9.ESD test:	□ Pass	□ NG ,		
10.Others:	□ Pass	□ NG ,		
Customer Signature:		<u>Date: / /</u>		